	Type	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	2	"200401584O9"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:36	
2	BRS	5	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3) with troubleshoot$3 and micro-fabrication	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 13:58	
3	BRS	1324	700/117,118,183,185.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/18 17:16	
4	BRS	1296	700/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:40	
5	BRS	440	714/46.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:41	
6	BRS	6	"6635872"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 14:47	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
7	IS&R	2	("5656811").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 13:43	
8	BRS	82	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3) with troubleshoot$3 and (micro-fabrication or fabrication) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 13:58	
9	IS&R	2	("5938424").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:54	

Type	Hits	Search Text	DBs	Time Stamp	Comments
10	BRS	82	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with troubleshoot$3 and (micro-fabrication or fabrication) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:53	
11	BRS	2	"20030120436"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 13:58	
12	BRS	8391	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:01	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
13	BRS	60	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charged with beam$1 and software	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:02	
14	BRS	5	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charged with beam$1 and software with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:03	

Type	Hits	Search Text	DBs	Time Stamp	Comments
15 BRS	7	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with beam$1 and software with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:03	
16 BRS	21	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with beam$1 and (program$4 or software$1) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:30	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
17	BRS	15	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (program$4 or software$1) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:04	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	18 5	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (program$4 or software$1 or cod$3) with execut$3 and user$1 with interface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:47	

Type	Hits	Search Text	DBs	Time Stamp	Comments
19 BRS	1	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or chip$1 or die$1) and (integrated adj circuit$1) or chip$1 or die$1) and (tow or dual) with charg$3 with beam$1 and (program$4 or software$1) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:33	
20 BRS	3	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (tow or dual) with charg$3 with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:33	

Type	Hits	Search Text	DBs	Time Stamp	Comments
21 IS&R	2	("6635872").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:47	
22 BRS	0	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with troubleshoot$3 and (micro-fabrication or fabrication) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and high with resolution with image$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:54	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	2	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with troubleshoot$3 and (micro-fabrication or fabrication) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and high with resolution with imag$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:56	
BRS	1173	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or IC$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:56	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	184	(troubleshoot$3 or inspect$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:57	
25					

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	70	(troubleshoot$3 or inspect$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3 and defect$1 with (file$1 dor database)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:58	

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Type	Hits	Search Text	DBs	Time Stamp	Comments
27 BRS	1	(troubleshoot$3 or inspect$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3 and initial$2 with defect$1 with (file$1 dor database)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:58	
28 BRS	107	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and chemical$2 with analy$4 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
29	BRS	4	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or chip$1 or die$1) or (integrated adj circuit$1) and chemical$2 with analy$4 with exposed with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:34	
30	BRS	11	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or IC$1 or wafer$1 or chip$1 or die$1) or (integrated adj circuit$1) and chemical$2 with analy$4 with expos$3 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:38	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
31	BRS	7	(analy$4 or diagnos$3). with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and EDS with tool$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:41	
32	BRS	1	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or IC$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and cross with section$2 with three with dimension and EDS with tool$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:41	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
33	BRS	1	(analys$4 or diagnos$$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and cross with section$2 with dimension and EDS with tool$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:42	
34	BRS	1	(analys$4 or diagnos$$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) and or chip$1 or die$1) and (cross-section$2 or (cross with section$2) with dimension and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:42	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	1	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:43	
BRS	142	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:06	

35

36

Type		Hits	Search Text	DBs	Time Stamp	Comments
37	BRS	1	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fails$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) with EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:43	
38	BRS	3	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fails$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) same EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:45	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
39	BRS	3	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and cut$4 with (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:53	
40	BRS	3	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and cut$4 with (cross-section$2 or (cross with section$2)) with (3-d or dimension$1 or three-dimension$2) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 16:21	

Type	Hits	Search Text	DBs	Time Stamp	Comments
		(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or integrated adj circuit$1 or chip$1 or die$1) and chemical$2 with analys$4 with surface$1			
41	BRS	307	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:29	
		(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or integrated adj circuit$1 or chip$1 or die$1) with chemical$2 with analys$4 with surface$1			
42	BRS	46	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:30	

Type	Hits	Search Text	DBs	Time Stamp	Comments
43 BRS	4	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) with chemical$2 with analy$4 with expos$3 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:32	
44 BRS	4	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) with chemical$2 adj analy$4 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
45	BRS	3	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and two with charg$3 with particles$1 with beam$1 and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:49	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	46	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:18	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	2	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) same charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:22	
47					

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	711	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) or charg$3 with particle$1 devices with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:04	
48					

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS 49	5	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with device$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:27	

Type	Hits	Search Text	DBs	Time Stamp	Comments
50 BRS	2	(analys$4 or diagnos$$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or chip$1 or die$1) and (integrated adj circuit$1) or chip$1 or die$1) and (dual or two) with charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:43	
51 BRS	2	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (dual or two) with charg$3 with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:44	

Type	Hits	Search Text	DBs	Time Stamp	Comments
52 BRS	12	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (dual or two) with charg$3 with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:45	
53 BRS	0	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and dual with charg$3, with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:45	

Type		Hits	Search Text	DBs	Time Stamp	Comments
54	BRS	5	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and dual with charg$3 with particle$1 with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:46	
55	BRS	6	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and dual same charg$3 with particle$1 with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:50	

Type	Hits	Search Text	DBs	Time Stamp	Comments
56 BRS	2	jp-11213935-$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:48	
57 BRS	45	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (two or dual) with charg$3 with particle$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:56	

Type	Hits	Search Text	DBs	Time Stamp	Comments
58 BRS	12	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (two or dual) adj beams and charg$3 with particle$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:00	
59 BRS	5	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:06	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	60	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3 and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:07	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	61	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$ and (program$4 or software$1 or cod$3) with execut$3 and user$1. with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:15	
	5				

	Type	Hits	Search Text	DBs	Time Stamp	Comments
62	BRS	58	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:16	
63	BRS	16	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:17	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	18 64	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) with beam$1 and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:20	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	65	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) adj beam$1 and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:25	

16

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	66	(analys$4 or diagnos$$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) adj beam$1 and user$1 with (interface or communicat$3) and computer with job$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:26	
	0				

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	16	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) adj beam$1 and user$1 with (interface or communicat$3) and computer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:26	

67

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	16	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) adj beam$1 and user$1 with (interface or communicat$3) with computer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 16:12	

68

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	69	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) adj beam$1 and user$1.with (interface or communicat$3) with computer and receiv$3 with request$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:34	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	44	(analys$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and ion with mill$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 16:45	
70					
IS&R	2	("6539106").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/15 17:02	
71					

Type	Hits	Search Text	DBs	Time Stamp	Comments
72 BRS	627	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat43 or adjust$3) with imag$3 with value$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:07	
73 BRS	773	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with imag$3 with value$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:07	

Type	Hits	Search Text	DBs	Time Stamp	Comments
74 BRS	53	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with imag$3 with value$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:08	
75 BRS	1	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with charged with particle with beam with parameter$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	

Type	Hits	Search Text	DBs	Time Stamp	Comments
76 BRS	1	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or chip$1 or die$1) or (integrated adj circuit$1) and (calibrat$3 or compensat$3 or adjust$3) with parameters$1 same charged with particle with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	
77 BRS	17	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with parameters$1 and charged with particle with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	

Type	Hits	Search Text	DBs	Time Stamp	Comments
78 BRS	17	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with parameter$1 and charged with particle with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	
79 BRS	1	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with parameter$1 and charged with particle with beam$1 and relocat$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:43	

Type	Hits	Search Text	DBs	Time Stamp	Comments
80 BRS	221	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:23	
81 BRS	11	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and SEM with chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:44	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	2	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and user$1 with (interface$1 or communication$1) with defin$3 with (condition$1 or state$1 or status$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	
BRS	1	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and pause same user$1 with (interface$1 or communication$1) with defin$3 with (condition$1 or state$1 or status$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:31	

Type	Hits	Search Text	DBs	Time Stamp	Comments
84 BRS	1	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and pause same user$1 with (interface$1 or communication$1) with defin$3 with (condition$1 or state$1 or status$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	
85 BRS	65	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and pause with user$1 with (interface$1 or communication$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	

Type	Hits	Search Text	DBs	Time Stamp	Comments
86 BRS	1	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and pause with user$1 with (interface$1 or communication$1) and defin$3 with (condition$1 or state$1 or status$1).	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	
87 BRS	3	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and pause with user$1 with (interface$1 or communication$1).	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 13:50	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
88	IS&R	2	("6539106").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/18 12:59	
89	BRS	320	analys$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and ion with beam$1 with electron with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 13:51	
90	BRS	401	analys$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and ion with beam$1 with electr$4 with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 13:51	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
91	BRS	5	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and ion with beam$1 with mill$3 with object$1 and electr$4 with beam$1 with imag$3 with object$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:02	
92	BRS	1	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and ion with beam$1 with mill$3 and electr$4 with beam$1 with imag$3 and computer with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 14:04	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	93	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and ion with beam$1 with mill$3 and electr$4 with beam$1 with imag$3 and computer and user$1 with (interface$1 or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 14:06	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	94 3	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and ion with beam$1 with mill$3 and electr$4 with beam$1 with imag$3 and computer and user$1 with (interface$1 or communicat$3) and (delet$3 or remov$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 14:06	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	39	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or chip$1 or die$1) (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3) with imag$3 with magnif$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:03	
96 BRS	13	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3) with imag$3 with magnif$7 and align$4 with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:17	

95

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	97	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3) with imag$3 with magnif$7 and align$4 with beam$1 and (relocat$3 or locat$3) with previous$2 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:07	

Note: second row shows "5" in Hits column.

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS 5	98	analys$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3) with imag$3 with magnif$7 and align$4 with beam$1 and (relocat$3 or locat$3 or re-locat$3) with previous$2 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:08	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	99	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3) with imag$3 with magnif$7 and align$4 with beam$1 and (relocat$3 or locat$3 or re-locat$3) with previous$2 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) and (adjust$3 or calibrat$3 or compensat$3) with charged with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:20	

Type	Hits	Search Text	DBs	Time Stamp	Comments
100 BRS	11	analys$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3) with charged with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:09	
101 BRS	1	analys$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3) with charged with beam$1 with parameter$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:09	

Type	Hits	Search Text	DBs	Time Stamp	Comments
102 BRS	2	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3). with imag$3 with magnif$7 and align$4 with beam$1 and (adjust$3 or calibrat$3 or compensat$3) with charged compensat$3) with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:17	

Type	Hits	Search Text	DBs	Time Stamp	Comments
103 BRS	2	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3) with imag$3 with magnif$7 and align$4 with beam$1 and (adjust$3 or calibrat$3 or compensat$3) with charg$3 or compensat$3) with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:17	

7/19/05, EAST Version: 2.0.1.4

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	104	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3) with image$3 with magnif$7 and align$4 with beam$1 and (relocat$3 or locat$3 or re-locat$3) with previous$2 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:21	

(Note: "5" appears to the right of "BRS" — in the Hits column reads 104, Type BRS, with a "5" marking.)

Type	Hits	Search Text	DBs	Time Stamp	Comments
105 BRS	1	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3 or modify$3 or chang$3) with imag$3 with magnif$7 and align$4 with beam$1 with parameter$1 and (relocat$3 or locat$3 or re-locat$3) with previous$2 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:22	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	106	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3 or modify$3 or chang$3) with imag$3 or magnif$7 and (relocat$3 or locat$3 or re-locat$3) with previous$2 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:23	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	107	analys$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3 or modify$3 or chang$3) with imag$3 with magnif$7 and (relocat$3 or locat$3 or re-locat$3) with (histor$6 or previous$2) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:24	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	5	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3 or modify$3 or chang$3) with imag$3 or magnif$7 and (relocat$3 or locat$3 or re-locat$3) with (histor$6 or previous$2) with imag$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:24	

108

Type	Hits	Search Text	DBs	Time Stamp	Comments
109 BRS	6	analy$4 same (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (adjust$3 or calibrat$3 or compensat$3 or modify$3 or chang$3) with imag$3 with magnif$7 and (relocat$3 or locat$3 or re-locat$3) with (histor$6 or previous$2) with imag$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:26	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	110	analy$4 same (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charged with beam$1 and (adjust$3 or calibrat$3 or compensat$3 or modify$3 or chang$3) with imag$3 with magnif$7 and (relocat$3 or locat$3 or re-locat$3) with (histor$6 or previous$2) with imag$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:27	

Type	Hits	Search Text	DBs	Time Stamp	Comments
111 BRS	6	analy$4 same (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or chip$1 or die$1) and (integrated adj circuit$1) or charged with beam$1 and control$5 with stage$1 with receiv$3 with (position$3 or locat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:48	
112 BRS	2	analy$4 same (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or chip$1 or die$1) and (integrated adj circuit$1) or charged with beam$1 and control$5 with stage$1 with receiv$3 with (position$3 or locat$4) with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:48	

Type	Hits	Search Text	DBs	Time Stamp	Comments
113 BRS	17	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 with (two or dual)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 16:41	
114 BRS	1	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or IC$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 with (two or dual) and path$1 with travel$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 16:43	

Type	Hits	Search Text	DBs	Time Stamp	Comments
115 BRS	807	702/183.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/18 17:15	
116 BRS	2102	702/117,118,183,185.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/18 17:16	